



Product Change Notification

110940 - 03

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 110940 - 03
Change Title: Intel® Desktop Board DH61WW, GbE LAN, Boxed and Bulk
PCN 110940-03, Product Design, Product Material
BIOS update, iTE PCIe to PCI bridge stepping, CPU socket cover changes
Reason for Revision: Correction due to change implementation.
Date of Publication: January 16, 2012

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Nov 28, 2011
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Description of Change to the Customer:

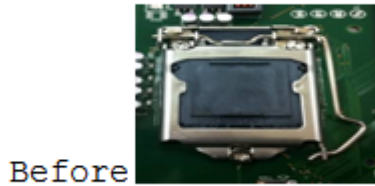
Reason for Revision: Correction due to change implementation.

The PCB Change has been removed from this PCN and being implemented later. See PCN 111182-01.

The following changes will be made:

1. The BIOS will be updated from BEH6710H.86A.0020 to BEH6110H.86A.0034. To access the release notes or get a copy of the BIOS for evaluation, go to <http://downloadcenter.intel.com>.
2. I/O shield will not be changed at this time
3. The iTE PCIe-to-PCI bridge controller (at reference designator location IU4A) will be changed from the C version to E version to improve compatibility.

4. The CPU socket cover will be changed to the ILM version as shown below:



Customer Impact of Change and Recommended Action:

It is recommended that customers evaluate this new BIOS to ensure a smooth transition. This change has been thoroughly evaluated to ensure that there are no quality or reliability implications to our customers. Intel validation of a new board revision does not include testing with older versions of BIOS. This change is not expected to cause a change to the Microsoft Windows* operating system's software driver stack.

The iTE PCIe-to-PCI bridge reports a "New device detected" in some operating systems. Microsoft* Windows will display a message and automatically install the necessary drivers; however customers may wish to update their OS image to avoid the message.

These changes have been thoroughly evaluated to ensure that there are no quality, reliability or functional implications to our customers. Intel is not recommending additional qualification of these changes on platforms received from Intel.

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change AA	Post Change AA
LADH61WWB3	915046	G39552-204	G39552-205
BOXDH61WWB3	915113	G23116-204	G23116-205
BLKDH61WWB3	915114	G23116-204	G23116-205

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
August 16, 2011	00	Originally Published PCN
September 30, 2011	01	Add BIOS update, iTE PCIe to PCI bridge stepping change, I/O shield & CPU socket cover change
November 30, 2011	02	BIOS change and I/O shield change removal
January 16, 2012	03	Correction due to change implementation.